



## Material Content Data Sheet



<b>Sales Product Name</b>	TLE7738G			<b>Issued</b>	28. August 2013			
<b>MA#</b>	MA001015600							
<b>Package</b>	PG-DSO-52-4			<b>Weight*</b>	872.47 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	27.549	3.16	3.16	31575	31575
leadframe	inorganic material	phosphorus	7723-14-0	0.073	0.01		84	
	non noble metal	zinc	7440-66-6	0.293	0.03		335	
	non noble metal	iron	7439-89-6	5.854	0.67		6710	
wire	non noble metal	copper	7440-50-8	237.701	27.24	27.95	272445	279574
	noble metal	gold	7440-57-5	3.710	0.43	0.43	4253	4253
	encapsulation	organic material	carbon black	1333-86-4	1.163	0.13		1332
encapsulation	plastics	epoxy resin	-	53.478	6.13		61294	
	inorganic material	silicondioxide	60676-86-0	526.640	60.36	66.62	603617	666243
leadfinish	non noble metal	tin	7440-31-5	7.508	0.86	0.86	8606	8606
plating	noble metal	silver	7440-22-4	0.968	0.11	0.11	1109	1109
glue	plastics	epoxy resin	-	1.885	0.22		2160	
	noble metal	silver	7440-22-4	5.654	0.65	0.87	6480	8640
*deviation	< 10%			Sum in total:		100,00		1000000

### Important Remarks:

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